



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20240605000.2

**Add Cu as Alternative Wire Base Metal for Selected Device(s)
Change Notification / Sample Request**

Date: June 05, 2024

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20240605000.2
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISO1540QDRQ1	NULL
ISO1541QDRQ1	NULL
ISO1640BQDRQ1	NULL
ISO6720BQDRQ1	NULL
ISO6720FBQDRQ1	NULL
ISO6721BQDRQ1	NULL
ISO6721FBQDRQ1	NULL
UCC5350SBQDRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240605000.2			PCN Date:	June 05, 2024								
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)												
Customer Contact:	Change Management team		Dept:	Quality Services									
Proposed 1st Ship Date:	December 02, 2024		Sample requests accepted until:	July 05, 2024									
*Sample requests received after July 05, 2024 will not be supported.													
Change Type:													
<input type="checkbox"/> Assembly Site	<input type="checkbox"/>	Design		<input type="checkbox"/>	Wafer Bump Material								
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/>	Data Sheet		<input type="checkbox"/>	Wafer Bump Process								
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change		<input type="checkbox"/>	Wafer Fab Site								
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/>	Test Site		<input type="checkbox"/>	Wafer Fab Material								
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process		<input type="checkbox"/>	Wafer Fab Process								
PCN Details													
Description of Change:													
Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:													
<table border="1" style="width: 100%;"> <thead> <tr> <th>Material</th> <th>Current*</th> <th>Proposed</th> </tr> </thead> <tbody> <tr> <td>Wire type</td> <td>0.96mil Au, 1.0mil Cu</td> <td>0.8mil Cu</td> </tr> </tbody> </table>						Material	Current*	Proposed	Wire type	0.96mil Au, 1.0mil Cu	0.8mil Cu		
Material	Current*	Proposed											
Wire type	0.96mil Au, 1.0mil Cu	0.8mil Cu											
Note: * - Au wire: Die to die bonding, Cu wire: Die to leadframe													
Reason for Change:													
Continuity of supply.													
<ol style="list-style-type: none"> 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock 													
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):													
None													
Impact on Environmental Ratings:													
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.													
<table border="1" style="width: 100%;"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>						RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change			
RoHS	REACH	Green Status	IEC 62474										
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change										
Changes to product identification resulting from this PCN:													
None													
Product Affected:													
ISO1540QDRQ1	ISO1640BQDRQ1	ISO6720FBQDRQ1	ISO6721FBQDRQ1										
ISO1541QDRQ1	ISO6720BQDRQ1	ISO6721BQDRQ1	UCC5350SBQDRQ1										

Qualification Report
 Automotive Qualification Summary
 (As per AEC-Q100 and JEDEC Guidelines)
 Approve Date 01-May-2024

Product Attributes

Attributes		Qual Device: ISO6721RBQDRQ1	QBS Package Reference: ISO6721BQDRQ1	QBS Package Reference: TLV9022QDRQ1	QBS Process Reference: UCC23513QDWYQ1	QBS Product Reference: ISO1640QDWRQ1
Automotive Grade Level		Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)		-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function		Interface	Interface	Signal Chain	Power Management	Interface
Wafer Fab Supplier		RFAB, RFAB	MH8, MH8	RFAB	RFAB, RFAB	RFAB, RFAB
Assembly Site		MLA	MLA	MLA	TAI	MLA
Package Group		SOIC	SOIC	-	SOIC	SOIC
Package Designator		D	D	D	DWY	DW
Pin Count		8	8	8	6	16

QBS: Qual By Similarity

Qual Device ISO6721RBQDRQ1 is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO6721RBQDRQ1	QBS Package Reference: ISO6721BQDRQ1	QBS Package Reference: TLV9022QDRQ1	QBS Process Reference: UCC23513QDWYQ1	QBS Product Reference: ISO1640QDWRQ1
Test Group A - Accelerated Environment Stress Tests												
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	-	No Fails	No Fails	-	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	1/12/0	-	-	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	3/135/0	-	-	-
Test Group B - Accelerated Lifetime Simulation Tests												
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	3/231/0	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-
Test Group C - Package Assembly Integrity Tests												
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/228/0	3/90/0	-	1/30/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/228/0	3/90/0	-	1/30/0

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO6721RBQDRQ1	QBS Package Reference: ISO6721BQDRQ1	QBS Package Reference: TLV9022QDRQ1	QBS Process Reference: UCC23513QDWYQ1	QBS Product Reference: ISO1640QDWWRQ1
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	-	-	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	3/30/0	3/30/0	-	-
Test Group D - Die Fabrication Reliability Tests												
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests												
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
LU	E4	AEC Q100-004	1	6	Latch-Up	Per AEC Q100-004	-	1/3/0	1/6/0	1/6/0	1/6/0	1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	3/90/0	3/90/0	3/90/0	1/30/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com>

Qualification Report
Automotive Qualification Summary
(As per AEC-Q100 and JEDEC Guidelines)
Approve Date 05-April-2024

Product Attributes

Attributes		Qual Device: UCC5350MCQDRQ1	Qual Device: UCC5350MCQDRQ1	QBS Package Reference: IS06721BQDRQ1	QBS Process Reference: UCC23513Q0WYQ1	QBS Package Reference: AMC2C120RQ1	QBS Product Reference: UCC5389EC00WYQ1	QBS Product Reference: UCC5350MC00RQ1	QBS Package Reference: UCC215260DWRQ1	QBS Package Reference: IS05452DWR	QBS Package Reference: UCC5350SB00RQ1	QBS Package Reference: UCC21540DWRQ1
Automotive Grade Level		Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)		-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function		Signal Chain	Signal Chain	Interface	Power Management	Signal Chain	Interface	Interface	Power Management	Power Management	Signal Chain	Power Management
Wafer Fab Supplier		RFAB, RFAB	RFAB, RFAB	MH8, MH8	RFAB, RFAB	MH8, DM056	DP1DMS, DP1DMS	DP1DMS, DP1DMS	DP1DMS, DP1DMS, MH8	DP1DMS, DP1DMS, MH8	RFAB, RFAB	MH8, MH8, MH8
Assembly Site		TAI	MLA	MLA	TAI	MLA	TAI	TAI	MLA	MLA	MLA	TAI
Package Group		SOIC	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC
Package Designator		D	D	D	DWY	D	DWY	D	DW	DW	D	DW
Pin Count		8	8	8	6	8	8	8	16	16	8	14

QBS: Qual By Similarity

Qual Device UCC5350MCQDRQ1 is qualified at MSL2 260C

Qual Device UCC5350MCQDRQ1 is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: UCC5350MCQDRQ1	Qual Device: UCC5350MCQDRQ1	QBS Package Reference: IS06721BQDRQ1	QBS Process Reference: UCC23513Q0WYQ1	QBS Product Reference: AMC2C120RQ1	QBS Package Reference: UCC5389EC00WYQ1	QBS Product Reference: UCC5350MC00RQ1	QBS Package Reference: UCC215260DWRQ1	QBS Package Reference: IS05452DWR	QBS Package Reference: UCC5350SB00RQ1	QBS Package Reference: UCC21540DWRQ1	
Test Group A - Accelerated Environment Stress Tests																			
PC	A1	JEDEC J-STD-020 JEDEC J-STD-022-A113	3	77	Preconditioning	MSL1 260C	-	-	-	3/0/0	-	-	-	-	-	-	-		
PC	A1	JEDEC J-STD-020 JEDEC J-STD-022-A113	3	77	Preconditioning	MSL2 260C	-	-	1/0/0	-	-	3/0/0	-	-	3/0/0	1/0/0	1/0/0		
HAST	A2	JEDEC JESD022-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	1/77/0	-	2/154/0	
ACIUHAST	A3	JEDEC JESD022-A104 and JEDEC JESD022-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-	-	-	-	1/77/0	-	3/231/0	
ACIUHAST	A3	JEDEC JESD022-A104 and JEDEC JESD022-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	-	-	-	-	-	
TC	A4	JEDEC JESD022-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	-	-	-	1/77/0	-	2/154/0	
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	-	-	-	-	-	1/5/0	-	-	-	
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	1/12/0	-	-	-	-	-	-	-	-	
HTSL	A6	JEDEC JESD022-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-	-	-	-	1/45/0	-	1/45/0
HTSL	A6	JEDEC JESD022-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	3/135/0	-	-	-	-	-	-	-	-	
Test Group B - Accelerated Lifetime Simulation Tests																			
HTOL	B1	JEDEC JESD022-A108	3	77	Life Test	125C	1000 Hours	-	1/77/0	-	3/231/0	-	1/77/0	-	-	-	-	-	
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-	-	-	-	-	-	
Test Group C - Package Assembly Integrity Tests																			
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/0/0	3/228/0	-	3/0/0	-	-	-	-	1/30/0	3/90/0	
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	3/228/0	-	3/0/0	-	-	-	-	1/30/0	3/90/0	
SD	C3	JEDEC J-STD-002	1	15	Pb Solderability	>95% Lead Coverage	-	-	-	1/15/0	-	1/15/0	-	-	-	-	-	-	
SD	C3	JEDEC J-STD-002	1	15	Pb-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0	-	1/15/0	-	-	-	-	-	-	
PD	C4	JEDEC JESD022-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	3/0/0	-	3/0/0	-	-	-	-	-	1/10/0	-	
Test Group D - Die Fabrication Reliability Tests																			
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements											
TDOB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements											
HCI	D3	JESD61 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements											
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements											
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements											
Test Group E - Electrical Verification Tests																			
ESD	E2	AEC Q100-002	1	3	ESD HBM	-2000 Volts	-	-	-	-	1/3/0	1/3/0	-	-	-	1/3/0	-		
ESD	E3	AEC Q100-011	1	3	ESD CDM	-500 Volts	-	-	-	-	1/3/0	1/3/0	-	-	-	1/3/0	-		
LU	E4	AEC Q100-004	1	6	Latch-Up	Per AEC Q100-004	-	-	-	-	-	1/6/0	-	-	-	1/6/0	-		
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67, Room, hot, and cold	-	-	-	-	-	1/30/0	1/30/0	-	-	1/30/0	-		

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycle
Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Qualification Report
 Automotive Qualification Summary
 (As per AEC-Q100 and JEDEC Guidelines)
 Approve Date 19-October-2023

Product Attributes

Attributes		Qual Device: ISO6763QDWQRQ1	Qual Device: UCC21540QDWKRQ1	QBS Process Reference: UCC23513QDWYQ1	QBS Process Reference: ISO7741FQDWQ1	QBS Product Reference: ISO6763QDWQRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Interface	Power Management	Power Management	Interface	Interface	Interface
Wafer Fab Supplier	RFAB, RFAB	MH8, MH8, MH8	RFAB, RFAB	MH8, MH8	RFAB, RFAB	RFAB, RFAB
Assembly Site	MLA	TAI	TAI	TAI	MLA	MLA
Package Group	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC
Package Designator	DW	DWK	DWY	DW	DW	DW
Pin Count	16	14	6	16	16	16

QBS: Qual By Similarity

Qual Device ISO6763QDWQRQ1 is qualified at MSL2 260C

Qual Device UCC21540QDWKRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISO6763QDWQRQ1	Qual Device: UCC21540QDWKRQ1	QBS Process Reference: UCC23513QDWYQ1	QBS Process Reference: ISO7741FQDWQ1	QBS Product Reference: ISO6763QDWQRQ1
Test Group A - Accelerated Environment Stress Tests												
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	No Fails	No Fails	-	-	No Fails
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	-	-	1/77/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	3/231/0	3/231/0	-	-	1/77/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	-	-	1/77/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	1/5/0	-	-	1/5/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	3/135/0	3/135/0	-	-	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	-	1/45/0

Test Group B - Accelerated Lifetime Simulation Tests												
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	3/231/0	3/231/0	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	3/2400/0	-
Test Group C - Package Assembly Integrity Tests												
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	1/15/0	-	1/15/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-	-
Test Group D - Die Fabrication Reliability Tests												
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements				
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements				
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements				
NBTI	D4	-	-	-	Negative Bias Temperature Instability	-	-	Completed Per Process Technology Requirements				
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements				
Test Group E - Electrical Verification Tests												
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	Device specific data [1]	Device specific data [1]	-	-	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1500 Volts	Device specific data [1]	Device specific data [1]	-	-	1/3/0
LU	E4	AEC Q100-004	1	6	Latch-Up	Per AEC Q100-004	-	Device specific data [1]	Device specific data [1]	-	-	1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	3/90/0	3/90/0	3/90/0	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

[1] Change from hybrid Au and Cu wires to full Cu wire in assembly will not impact HBM, CDM, and LU result.

Qualification Report
Automotive Qualification Summary
(As per AEC-Q100 and JEDEC Guidelines)
Approve Date 16-June-2023

Product Attributes

Attributes	Qual Device: UCC21520QDWRQ1	Qual Device: ISO5452DWR	QBS Reference: UCC21520QDWRQ1	QBS Reference: ISO5851QDWRQ1	QBS Reference: TMP451AQDWRQ1	QBS Reference: AMC1305M25QDWRQ1	QBS Reference: AMC1305M25QDWRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Power Management	Interface	Power Management	Signal Chain	Signal Chain
Wafer Fab Supplier	DP1DM5, DP1DM5, DP1DM5	DP1DM5, DP1DM5, DP1DM5, MH8	DP1DM5, DP1DM5, DP1DM5	MH8, DP1DM5, DP1DM5	DP1DM5	DP1DM5, DP1DM5, AIZU	DP1DM5, DP1DM5, AIZU
Assembly Site	TAI	MLA	TAI	TAI	UTL1	MLA	TAI
Package Group	SOIC	SOIC	SOIC	SOIC	QFN	SOIC	SOIC
Package Designator	DW	DW	DW	DW	DQF	DW	DW
Pin Count	16	16	16	16	8	16	16

QBS: Qual By Similarity

Qual Device UCC21520QDWRQ1 is qualified at MSL2 260C

Qual Device ISO5452DWR is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: UCC21520QDWRQ1	Qual Device: ISO5452DWR	QBS Reference: UCC21520QDWRQ1	QBS Reference: ISO5851QDWRQ1	QBS Reference: TMP451AQDWRQ1	QBS Reference: AMC1305M25QDWRQ1	QBS Reference: AMC1305M25QDWRQ1
Test Group A - Accelerated Environment Stress Tests														
PC	A1	JEDEC J-STD-020 JEDEC22-A113	3	77	Preconditioning	MSL1 260C	-	-	-	-	-	No Fails	-	-
PC	A1	JEDEC J-STD-020 JEDEC22-A113	3	77	Preconditioning	MSL2 260C	-	No Fails	No Fails	No Fails	No Fails	-	-	-
PC	A1	JEDEC J-STD-020 JEDEC22-A113	3	77	Preconditioning	MSL3 260C	-	-	-	-	-	-	3/0/0	3/0/0
HAST	A2	JEDEC JEDEC22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	-	3/231/0	3/231/0	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JEDEC22-A102/JEDEC JEDEC22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	1/77/0	1/77/0	1/77/0	3/231/0	3/231/0	3/231/0
TC	A4	JEDEC JEDEC22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	1/77/0	1/77/0	3/231/0	3/231/0	3/231/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	1/5/0	-	-	1/5/0	1/5/0	1/5/0
HTSL	A6	JEDEC JEDEC22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	1/45/0	-	-	-	3/135/0	3/135/0
HTSL	A6	JEDEC JEDEC22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	1/45/0	-	-
Test Group B - Accelerated Lifetime Simulation Tests														
HTOL	B1	JEDEC JEDEC22-A108	1	77	Life Test	125C	1000 Hours	-	-	-	3/231/0	-	-	-
HTOL	B1	JEDEC JEDEC22-A108	1	77	Life Test	150C	408 Hours	-	-	-	3/231/0	-	-	-
ELFR	B2	AEC Q100-008	1	77	Early Life Failure Rate	125C	48 Hours	-	-	-	3/240/0	-	-	-
ELFR	B2	AEC Q100-008	1	77	Early Life Failure Rate	150C	24 Hours	-	-	-	3/240/0	-	-	-
Test Group C - Package Assembly Integrity Tests														
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	-	1/30/0	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	-	1/30/0	3/90/0	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	-	-	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	-	-	-	-
PD	C4	JEDEC JEDEC22-B100 and B108	1	10	Physical Dimensions	Cpk>1.67	-	-	-	-	1/10/0	3/30/0	-	-
Test Group D - Die Fabrication Reliability Tests														

EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements						
TDBB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements						
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements						
NBTI	D4	-	-	-	Negative Bias Temperature Instability	-	-	Completed Per Process Technology Requirements						
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements						
Test Group E - Electrical Verification Tests														
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	Device specific data [1]	Device specific data [1]	1/3/0	1/3/0	1/3/0	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	Device specific data [1]	Device specific data [1]	1/3/0	1/3/0	1/3/0	-	-
LU	E4	AEC Q100-004	1	6	Latch-Up	Per AEC Q100-004	-	Device specific data [1]	Device specific data [1]	1/6/0	1/6/0	1/6/0	-	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/3/0	1/3/0	1/3/0	1/3/0	3/90/0	3/90/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2203-108

[1] Qual Device: UCC21520QDWQ1 and QBS Reference: UCC21520QDWQ1 use the same silicon die and bondout.

Qual Device: ISO5452DWR and QBS Reference: ISO5851QDWQ1 use the same silicon die and bondout.

Qualification Report

Automotive Qualification Summary

(As per AEC-Q100, AEC-Q006, and JEDEC Guidelines)

Approve Date 28-April-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC1305M25QDWQ1	Qual Device: AMC1305M25QDWQ1
Test Group A - Accelerated Environment Stress Tests									
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	1 Step	No Fails	No Fails
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	1 Step	3/66/0	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	1 Step	3/66/0	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-

HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	-	-
HAST	A2.1.3	-	3	30	Wire Bond Shear, post bHAST, 1X	Post stress	Wires	-	-
HAST	A2.1.4	-	3	30	Bond Pull over Stitch, post bHAST, 1X	Post stress	Wires	-	-
HAST	A2.1.5	-	3	30	Bond Pull over Ball, post bHAST, 1X	Post stress	Wires	-	-
HAST	A2.2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	192 Hours	3/231/0	3/231/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	3/66/0	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	3/3/0	3/3/0
HAST	A2.2.3	-	3	30	Wire Bond Shear, post bHAST, 2X	Post stress	Wires	3/9/0	3/9/0
HAST	A2.2.4	-	3	30	Bond Pull over Stitch, post bHAST, 2X	Post stress	Wires	3/9/0	3/9/0
HAST	A2.2.5	-	3	30	Bond Pull over Ball, post bHAST, 2X	Post stress	Wires	3/9/0	3/9/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	-	-
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	-	-
TC	A4.1.3	-	3	30	Wire Bond Shear, post TC, 1X	Post stress	Wires	-	-
TC	A4.1.4	-	3	30	Bond Pull over Stitch, post TC, 1X	Post stress	Wires	-	-
TC	A4.1.5	-	3	30	Bond Pull over Ball, post TC, 1X	Post stress	Wires	-	-
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	1000 Cycles	3/210/0	3/210/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	3/66/0	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	3/3/0	3/3/0
TC	A4.2.3	-	3	30	Wire Bond Shear, post TC, 2X	Post stress	Wires	3/9/0	3/9/0
TC	A4.2.4	-	3	30	Bond Pull over Stitch, post TC, 2X	Post stress	Wires	3/9/0	3/9/0
TC	A4.2.5	-	3	30	Bond Pull over Ball, post TC, 2X	Post stress	Wires	3/9/0	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	3/135/0	3/135/0
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	-	-
HTSL	A6.2	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	2000 Hours	3/132/0	3/132/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	3/3/0	3/3/0

Test Group B - Accelerated Lifetime Simulation Tests									
Test Group C - Package Assembly Integrity Tests									
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-
PD	C4	JEDEC JESD22-B100 and B108	1	10	Physical Dimensions	Cpk>1.67	-	-	-
Test Group D - Die Fabrication Reliability Tests									
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
NBTI	D4	-	-	-	Negative Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements

QBS: Qual By Similarity

Qual Device AMC1305M25QDWQ1 is qualified at MSL3 260C

Qual Device AMC1305M25QDWQ1 is qualified at MSL3 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E) : -40C to +150C

Grade 1 (or Q) : -40C to +125C

Grade 2 (or T) : -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Qualification Report

Automotive Qualification Summary
 (As per AEC-Q100 and JEDEC Guidelines)
 (Q100, Q006, Grade 1, -40/125C)
 Approved 21-Dec-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Type	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: UCC21330BQDRQ1	QBS Reference Device: TLV9022QDRQ1	QBS Reference Device: ISO6721BQDRQ1
Test Group A - Accelerated Environment Stress Tests										
	PC	A1	-	3	22	SAM Analysis, <u>Pre Stress</u>	Completed	3/66/0	3/66/0	-
	PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	Level 2-260C	No fails	No fails	No fails
	PC	A1	-	3	22	SAM Analysis, Post Stress	Completed	3/66/0	3/66/0	2/44/0
	HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0
	HAST	A2	-	3	1	Cross Section, Post bHAST 96 Hours	Completed	-	-	-
	HAST	A2	-	3	30	Wire Bond Shear, Post bHast 96 Hours	Wires	-	-	-
	HAST	A2	-	3	30	Bond Pull over Stitch, post bHAST, 96 Hours	Wires	-	-	-
	HAST	A2	-	3	30	Bond Pull over Ball, Post bHAST, 96 Hours	Wires	-	-	-
	HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST, 130C/85%RH	192 Hours	-	3/210/0	3/210/0
	HAST	A2	-	3	1	Cross Section, Post bHAST 192 Hours	Completed	-	3/3/0	3/3/0
	HAST	A2	-	3	22	SAM Analysis, Post bHAST, 192 Hours	Completed	-	3/66/0	3/66/0
	HAST	A2	-	3	30	Wire Bond Shear, Post bHast 192 Hours	Wires	-	3/9/0	3/9/0
	HAST	A2	-	3	30	Bond Pull over Stitch, post bHAST, 192 Hours	Wires	-	3/9/0	3/9/0
	HAST	A2	-	3	30	Bond Pull over Ball, Post bHAST, 192 Hours	Wires	-	3/9/0	3/9/0
	TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0
	TC	A4	-	3	1	Cross Section, Post T/C 500 Cycles	Completed	-	-	-
	TC	A4	-	3	22	SAM Analysis, Post T/C, 500 Cycles	Completed	-	-	-

	Type	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: <u>UCC21330BQDRQ1</u>	QBS Reference Device: <u>TLV9022QDRQ1</u>	QBS Reference Device: <u>ISO6721BQDRQ1</u>
	TC	A4	-	3	30	Wire Bond Shear, Post T/C 500 Cycles	Wires	-	-	-
	TC	A4	-	3	30	Bond Pull over Stitch Post T/C 500 Cycles	Wires	-	-	-
	TC	A4	-	3	30	Bond Pull over Ball Post T/C 500 Cycles	Wires	-	-	-
	TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle, -65/150C	1000 Cycles	3/210/0	3/210/0	3/210/0
	TC	A4	-	3	1	Cross Section, Post T/C 1000 Cycles	Completed	3/3/0	3/3/0	3/3/0
	TC	A4	-	3	22	SAM Analysis, Post T/C, 1000 Cycles	Completed	3/66/0	3/66/0	3/66/0
	TC	A4	-	3	30	Wire Bond Shear, Post T/C 1000 Cycles	Wires	3/9/0	3/9/0	3/9/0
	TC	A4	-	3	30	Bond Pull over Stitch, Post T/C, 1000 Cycles	Wires	3/9/0	3/9/0	3/9/0
	TC	A4	-	3	30	Bond Pull over Ball, Post T/C, 1000 Cycles	Wires	3/9/0	3/9/0	3/9/0
	PTC	A5	JEDEC JESD22-A105	1	45	Power Temperature Cycle -40/125C	1000 Cycles	N/A	N/A	N/A
	PTC	A5	JEDEC JESD22-A105	1	45	Power Temperature Cycle -40/125C	2000 Cycles	N/A	N/A	N/A
	HTSL	A6	JEDEC JESD22-A103	3	45	High Temp Storage Bake 175C	500 Hours	-	3/231/0	3/135/0
	HTSL	A6	-	3	1	Cross Section, Post HTSL 1000 Hours	Completed	-	-	-
	HTSL	A6	JEDEC JESD22-A103	3	44	High Temp Storage Bake 150C	2000 Hours	-	3/210/0	3/132/0
	HTSL	A6	-	3	1	Cross Section, Post HTSL 2000 Hours	Completed	-	3/3/0	3/3/0
Test Group C – Package Assembly Integrity Tests										
	WBS	C1	AEC Q100-001	3	30	Wire Bond Shear, Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0
	WBP	C2	MIL-STD883 Method 2011	3	30	Bond Pull over Ball, Cpk >1.67	Wires	3/90/0	3/90/0	3/90/0

- QBS: Qual By Similarity

- Qual Device UCC21330BQDRQ1 is qualified at LEVEL2-260C

A1 (PC): Preconditioning:

Performed for THB, Biased HAST, AC, uHAST & TC samples, as applicable.

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

ZVEI ID: SEM-PA-08

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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